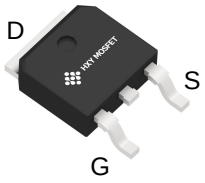
Description

The HXY60P02D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

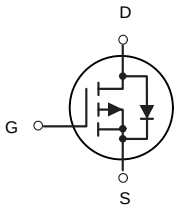


TO-252-2L

General Features

V_{DS} = -20V I_D =-60A

$R_{DS(ON)}$ < 8.5 mΩ@ V_{GS}=4.5V



P-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY60P02D	TO-252-2L	60P02 XXXX	2500

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-20	V
VGS	Gate-Source Voltage	±12	V
I_D@T_C=25°C	Continuous Drain Current, V_{GS} @ 10V[1]	-60	A
I_D@T_C=100°C	Continuous Drain Current, V_{GS} @ 10V[1]	-39	A
IDM	Pulsed Drain Current[2]	-240	A
P_D@T_C=25°C	Total Power Dissipation[4]	70	W
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta}JA$	Thermal Resistance Junction-ambient [1]	75	°C/W
$R_{\theta}JC$	Thermal Resistance Junction-Case[1]	4.2	°C/W

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V,I_D= -250μA	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = -20V, V_{GS} = 0V,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS} =0V, V_{GS} = ±12V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}= V_{GS}, I_D= -250μA	-0.35	-0.65	-1.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note3	V_{GS} =-4.5V, I_D =-15A	-	6.6	8.5	mΩ
		V_{GS} =-2.5V, I_D =-12A	-	8	12	
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} =-10V, V_{GS} =0V, f = 1.0MHz	-	4590	-	pF
C_{oss}	Output Capacitance		-	505	-	pF
C_{rss}	Reverse Transfer Capacitance		-	440	-	pF
Q_g	Total Gate Charge	V_{DS} =-10V, I_D =-15A, V_{GS} =-4.5V	-	46	-	nC
Q_{gs}	Gate-Source Charge		-	7.3	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	10	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DD} =-10V, I_D =-14A, R_{GEN}=2.7Ω, V_{GS} =-10V	-	8	-	ns
t_r	Turn-on Rise Time		-	59	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	111	-	ns
t_f	Turn-off Fall Time		-	43	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-60	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-240	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S =-20A	-	-	-1.2	V
trr	Reverse Recovery Time	T_J=25℃,I_{SD}=-15A, V_{GS}=0V di/dt=-100A/μs	-	18	-	ns
Qrr	Reverse Recovery Charge		-	7.7	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25°C,V_{DD}=-10V,V_G=-10V, R_G=5.9Ω, L=0.5mh,I_{AS}=-13.2A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Characteristics

Figure1: Output Characteristics

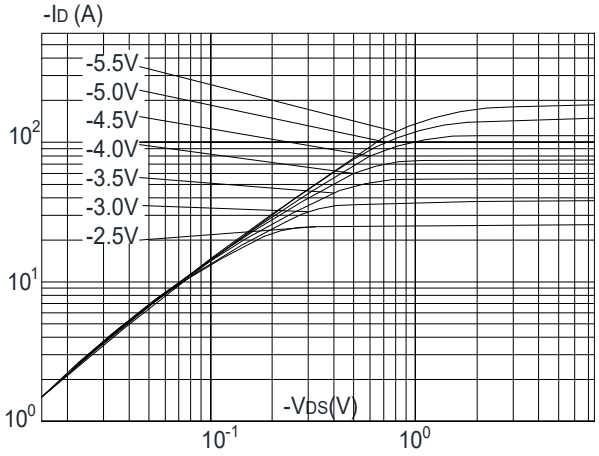


Figure 2: Typical Transfer Characteristics

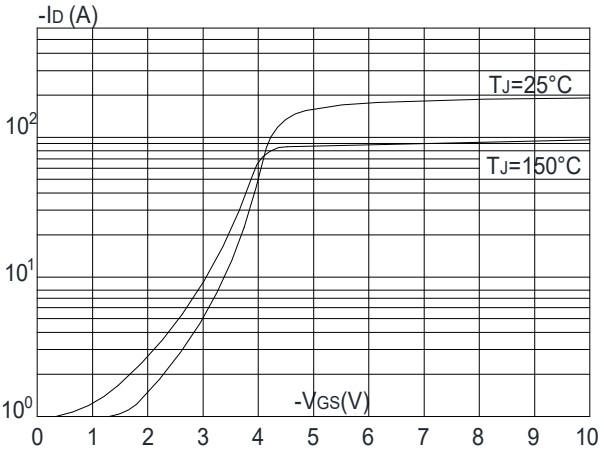


Figure 3: On-resistance vs. Drain Current

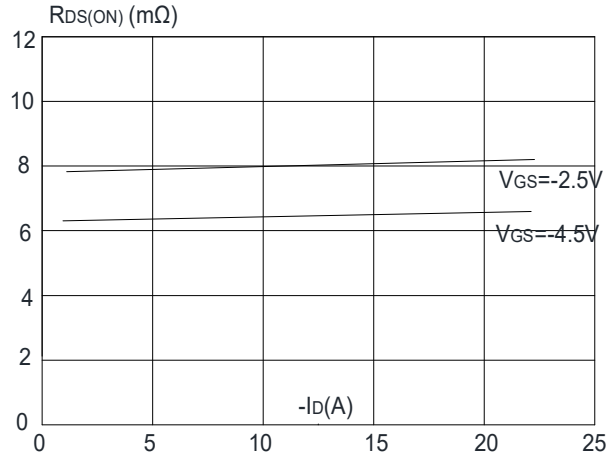


Figure 4: Body Diode Characteristics

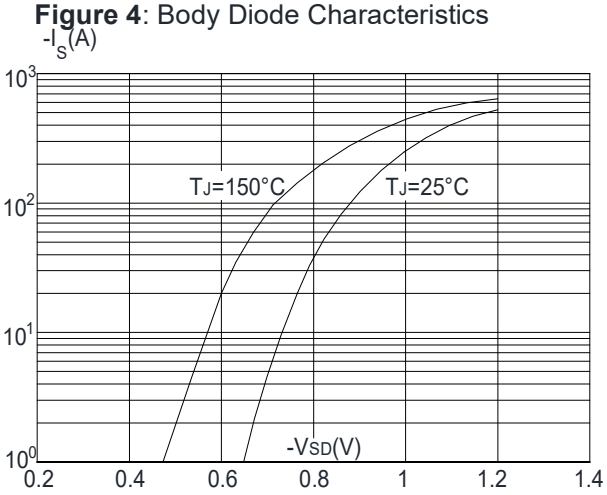


Figure 5: Gate Charge Characteristics

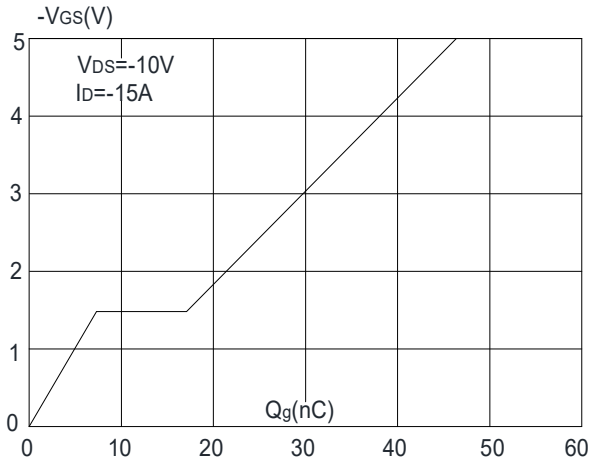


Figure 6: Capacitance Characteristics

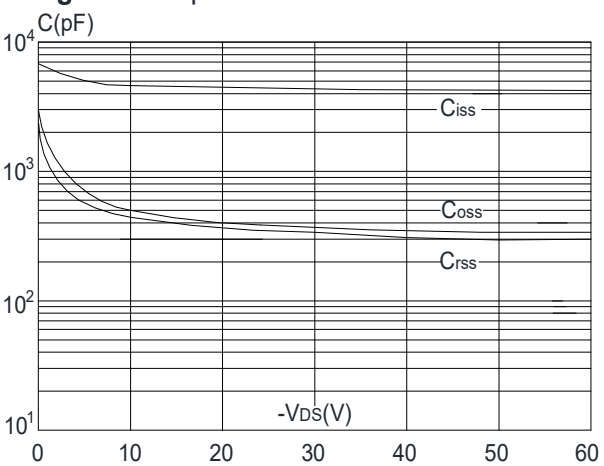


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

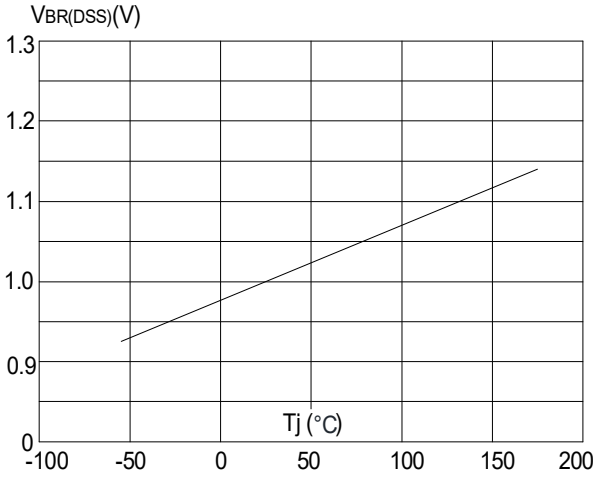


Figure 8: Normalized on Resistance vs. Junction Temperature

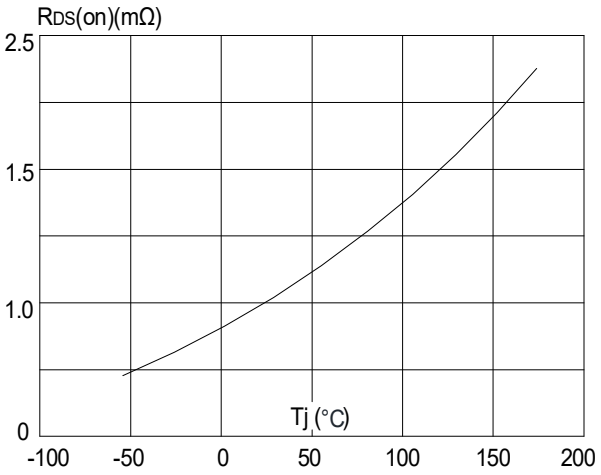


Figure 9: Maximum Safe Operating Area

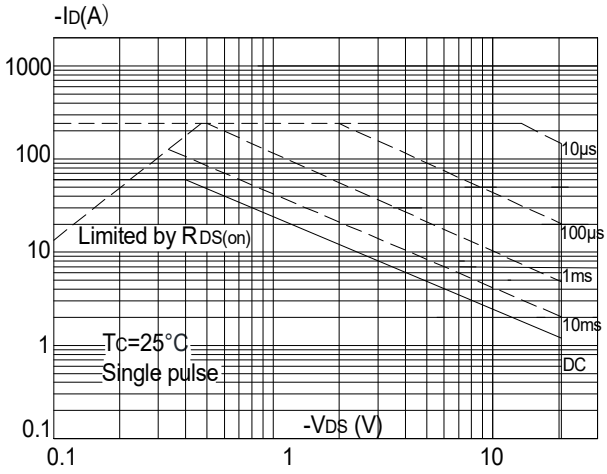


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

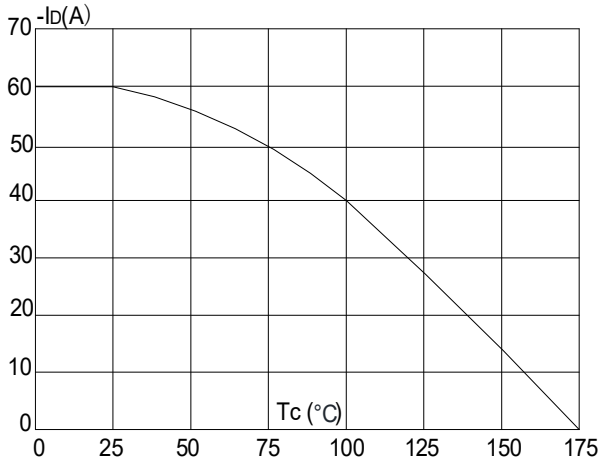
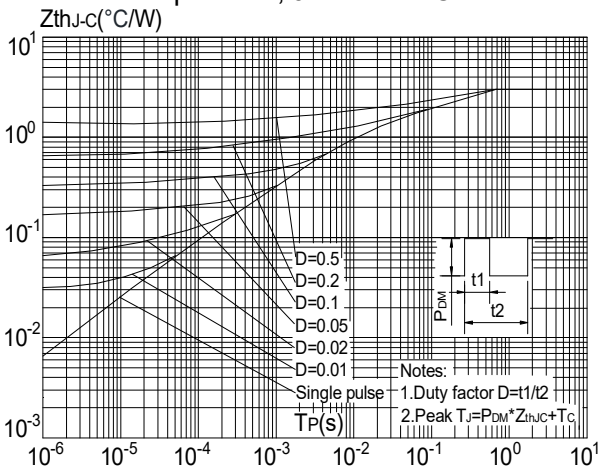
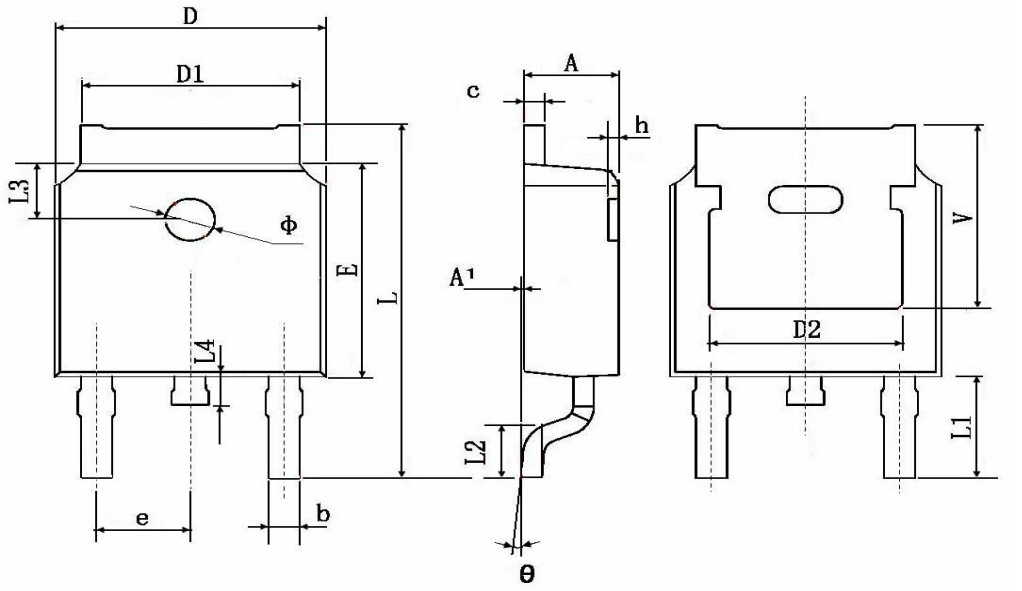


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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